



THE UNITED STATES PATENT AND TRADEMARK OFFICE

2813  
#12/12/01  
6/18/01  
RECEIVED  
MAY 17 2001  
TECHNICAL STAFF

In re application of

THEODORE W. HOUSTON

Serial No. 09/346,436 (TI-21004)

Filed July 1, 1999

For: BONDED SOI WITH BURIED INTERCONNECT TO HANDLE OR DEVICE WAFER

Art Unit 2813

Examiner E. Kielin

Commissioner for Patents  
Washington, D. C. 20231

Sir:

**AMENDMENT UNDER 37 C.F.R. 1.111**

In response to the Office action dated April 24, 2001, please amend the above-identified application as follows:

**In the claims:**

Amend claim 1 as follows:

1. (Thrice Amended) A method of fabricating an SOI structure which comprises the steps  
of:

(a) providing a substrate having at least one of active or passive elements on a surface  
thereof;

(b) providing [and] a device wafer having at least one of active or passive elements on a  
surface thereof;